

Title (en)

PROCESS AND DEVICE FOR BRINGING TOGETHER, ALIGNING AND JOINT PROCESSING OF LIMP WORKPIECE LAYERS.

Title (de)

VERFAHREN UND VORRICHTUNG ZUM ZUSAMMENFÜHREN, AUSRICHTEN UND GEMEINSAMEN VERARBEITEN VON BIEGESCHLAFFEN WERKSTÜCKLAGEN.

Title (fr)

PROCEDE ET DISPOSITIF POUR REUNIR, ALIGNER ET TRAITER CONJOINTEMENT DES NAPPES DE PIECES MOLLES.

Publication

**EP 0493492 B1 19931215 (DE)**

Application

**EP 90914697 A 19900918**

Priority

DE 3931673 A 19890922

Abstract (en)

[origin: WO9104365A1] The workpiece layers to be processed are suspended in a vertical plane and fed automatically to a scanning and alignment station (R). To this end, the workpiece layers are gripped in a horizontal starting position, moved into the vertical position and conveyed to the scanning and alignment station (R). After alignment, they are taken immediately and transported to the processing station (N). The device for carrying out this process has two conveying devices (F, F'), each consisting of a feed conveyor (Z; Z') in the form of a manipulator and a transport device (T; T') formed by a conveyor belt (48; 48'). The workpiece layers are held in the scanning and alignment station (R) by mechanically movable clamps (20; 20'). The transport devices (T; T') can be moved to an d fro between a driving and a non-driving position in the region of the clamps (20; 20'). This enables the feed conveyors (Z, Z') to transfer the workpiece layers to the clamps (20; 20'), which can then be moved freely in order to align the workpiece layers with each other.

IPC 1-7

**D05B 33/02; A41H 43/02**

IPC 8 full level

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